

Highly-dense Mixed Grained Reconfigurable Architecture with Via-switch

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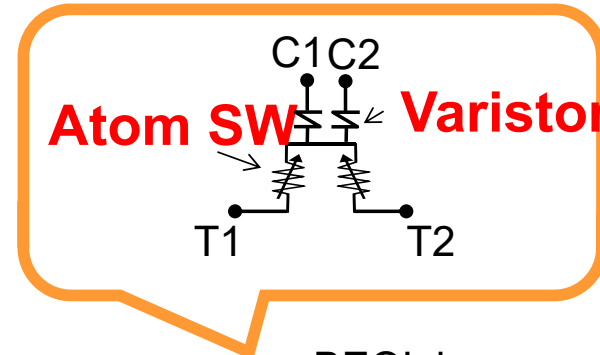
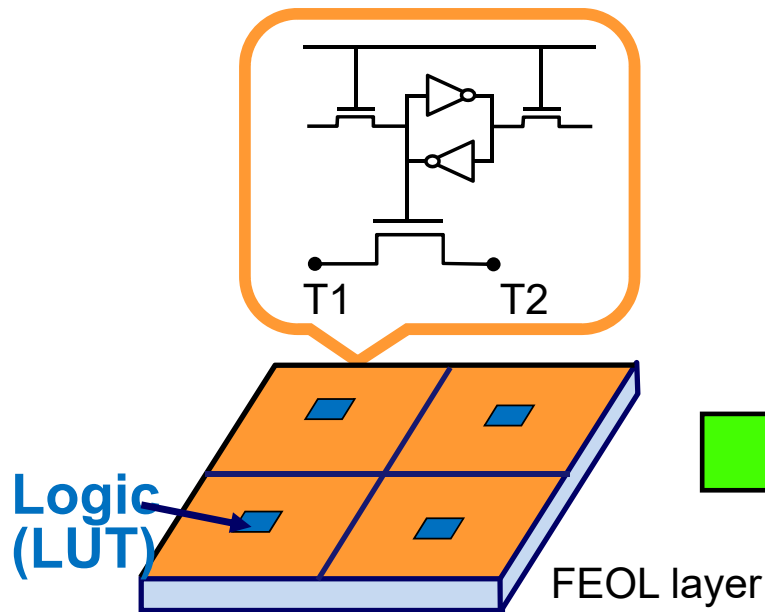
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Contribution

26X higher density
66% smaller interconnect delay at 0.5V

SRAM + MOS SW in FEOL

***“Via-switch”* in BEOL**



**Logic
(Arithmetic/Memory
Unit+MUX for LUT)**

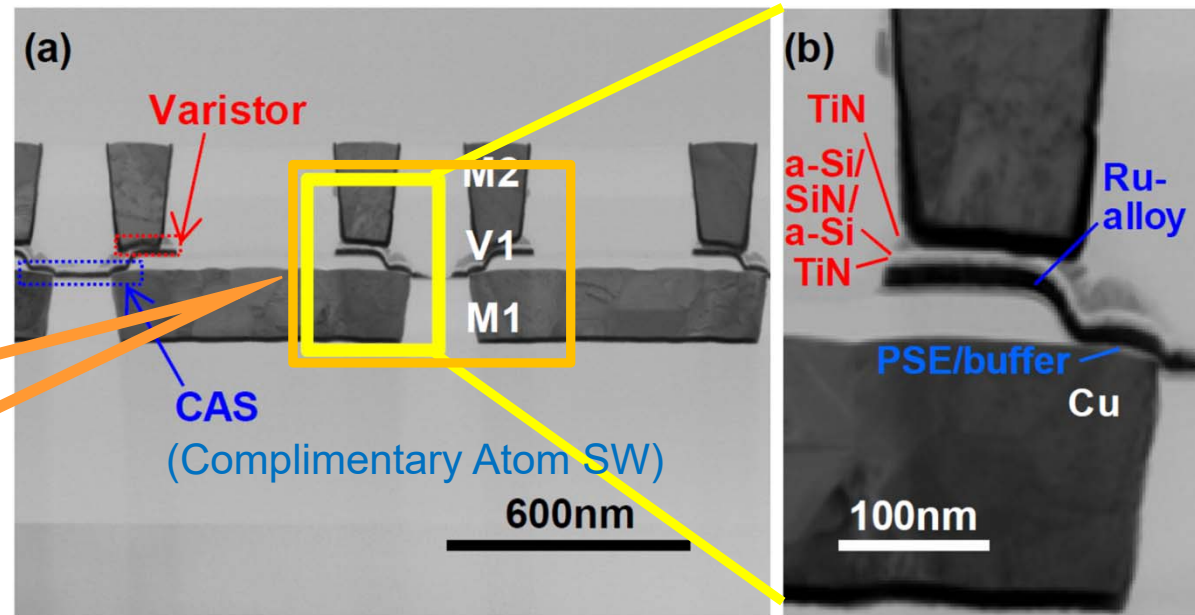
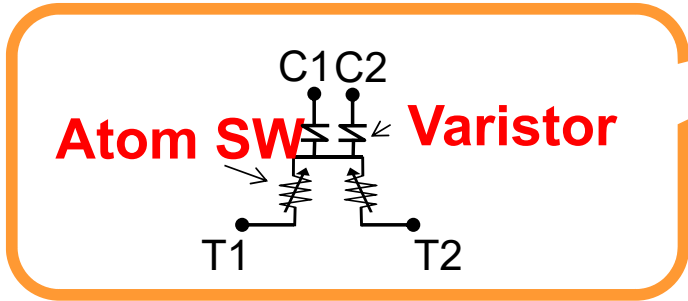
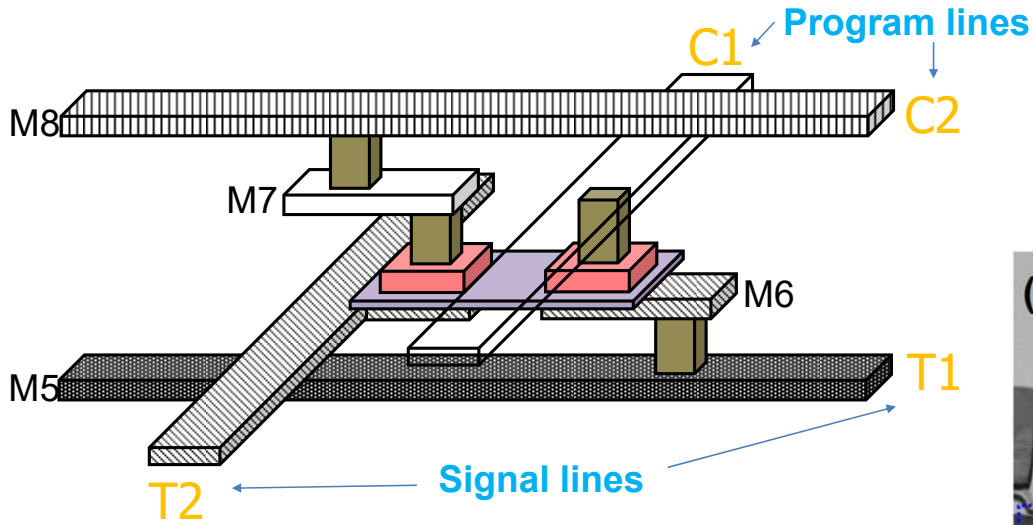
Conventional FPGA

Proposed Architecture

Via-switch

Access Tr. unnecessary for programming

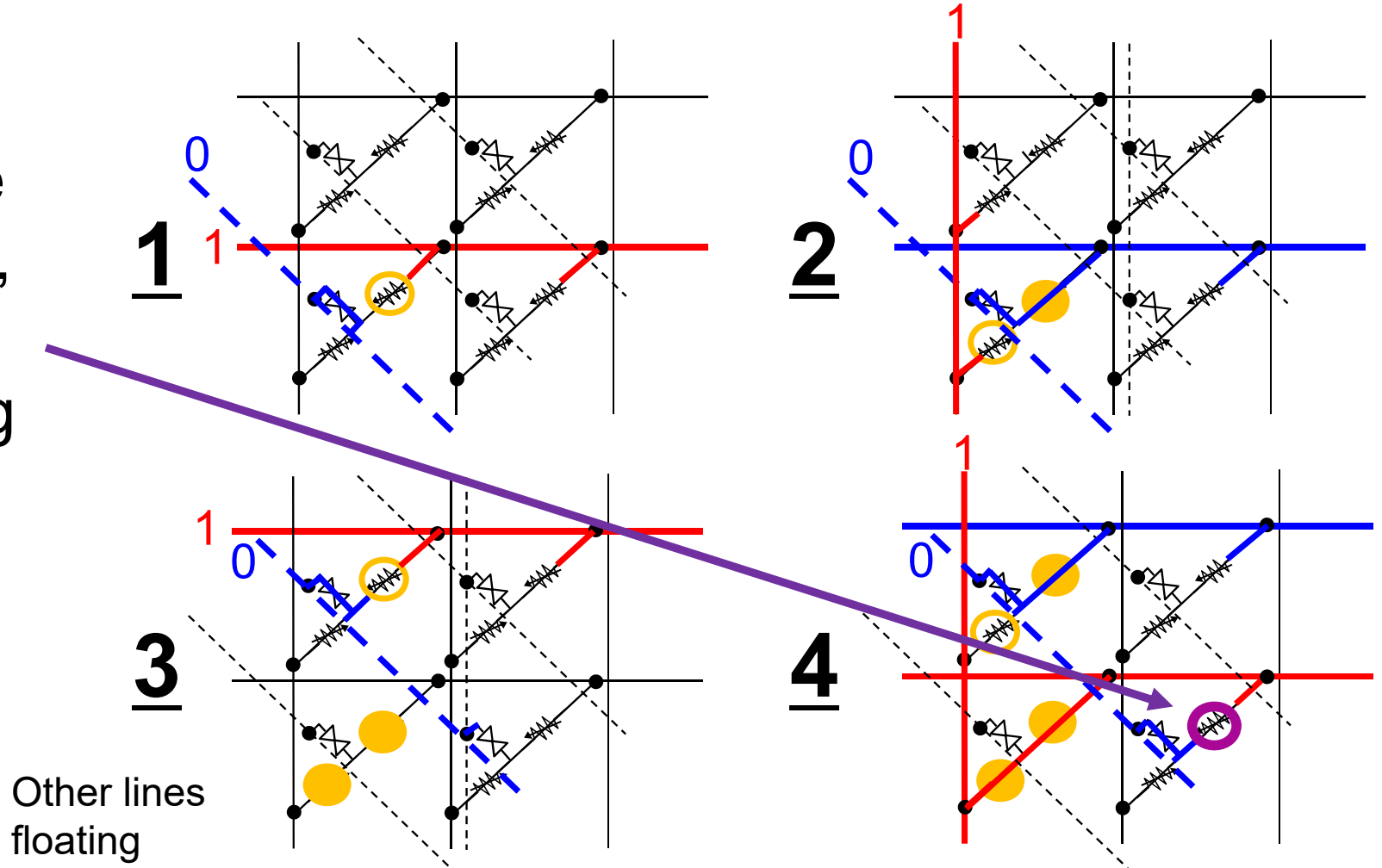
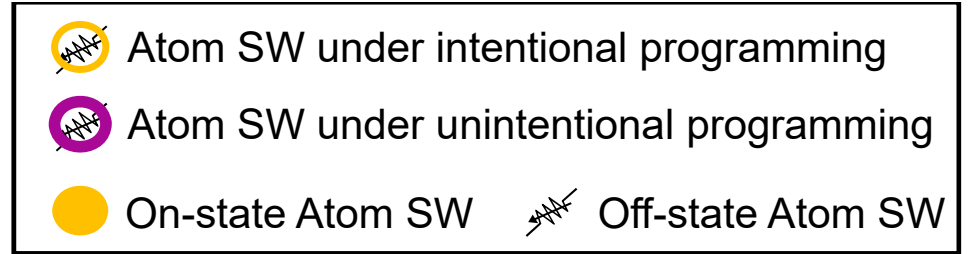
[Banno, IEDM2015]



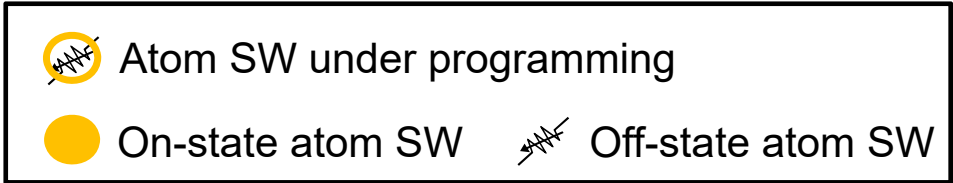
Atom SW: Electrochemical nonvolatile R-change device
On-R can be reduced to 200Ω.

Why two program lines?

With a single program line, unintentional programming will happen.



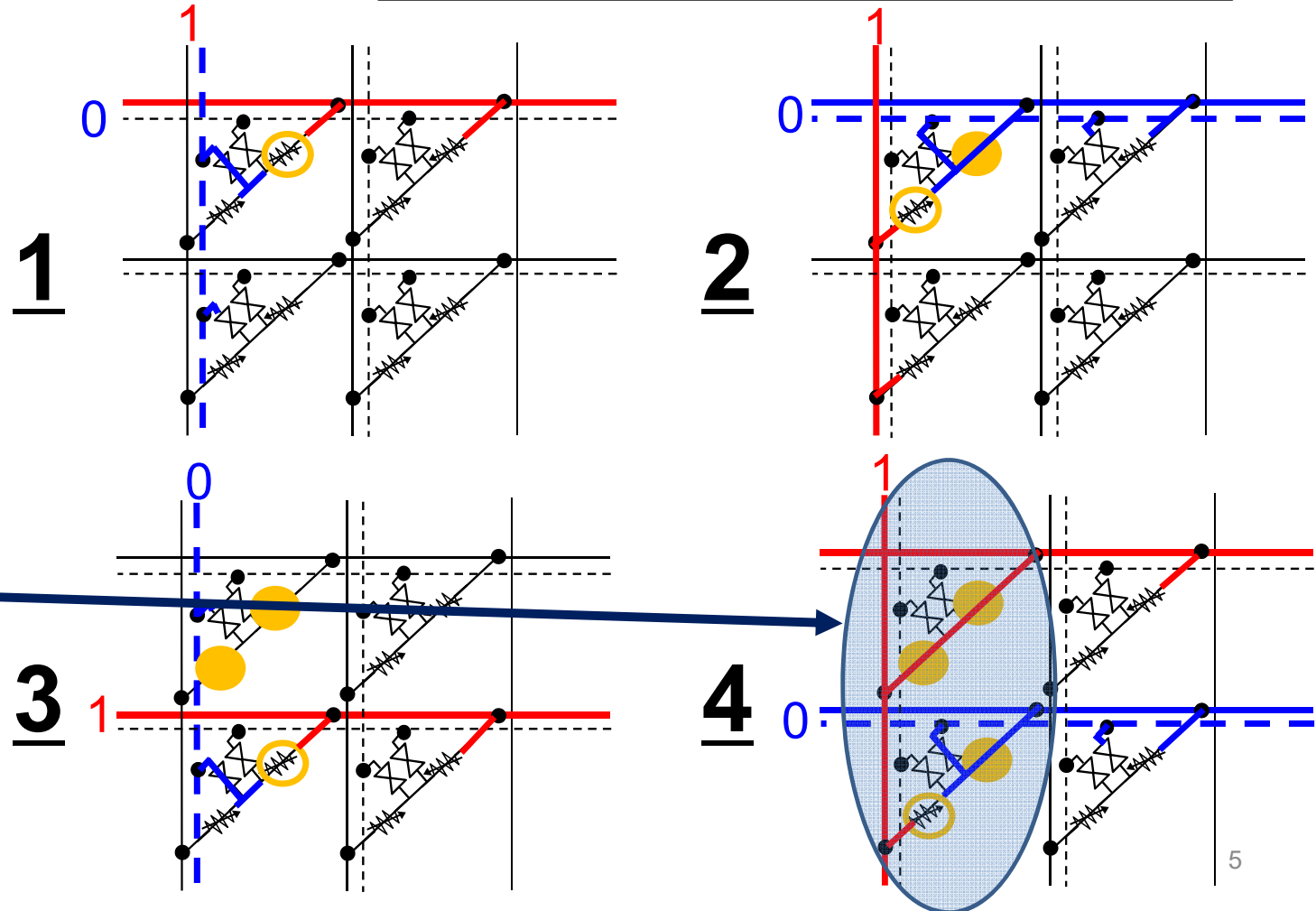
Why two program lines?



With two program lines, unintentional programming will not happen.

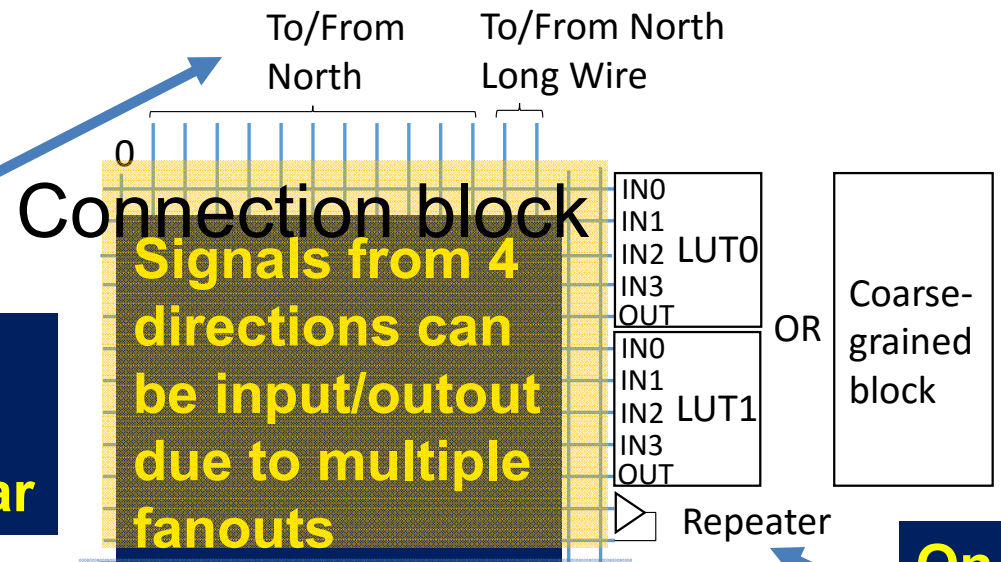
Multiple-ON in a column enables multiple fanouts.

Other lines floating

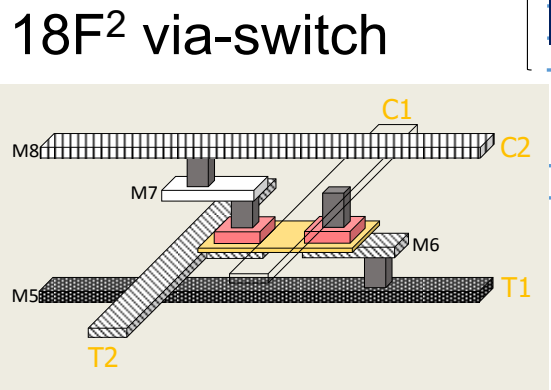
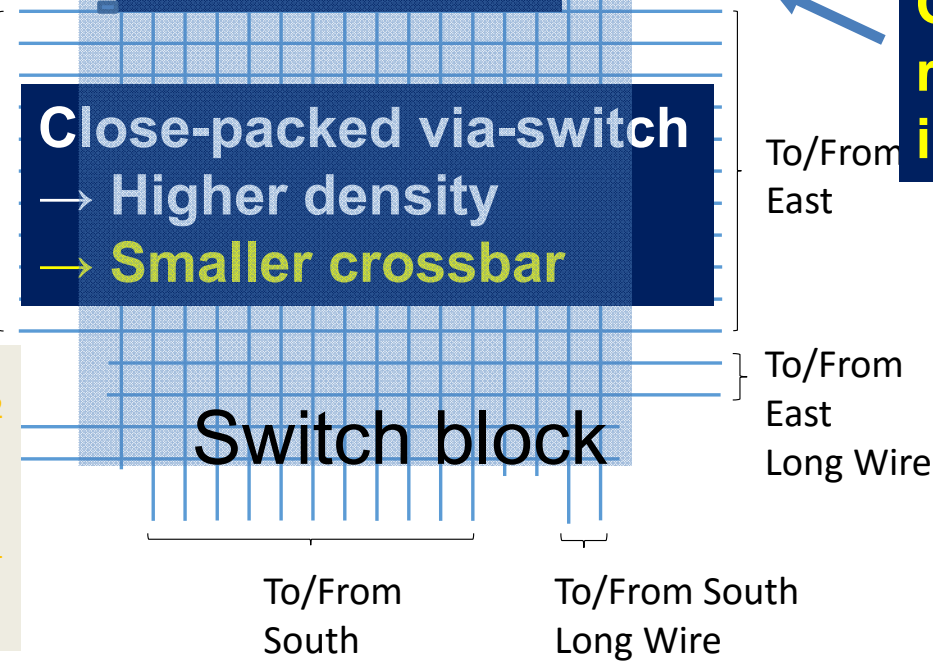


Proposed crossbar structure

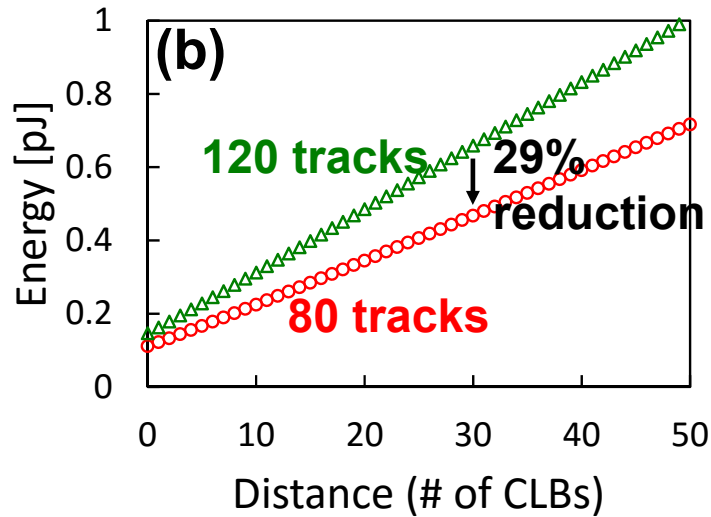
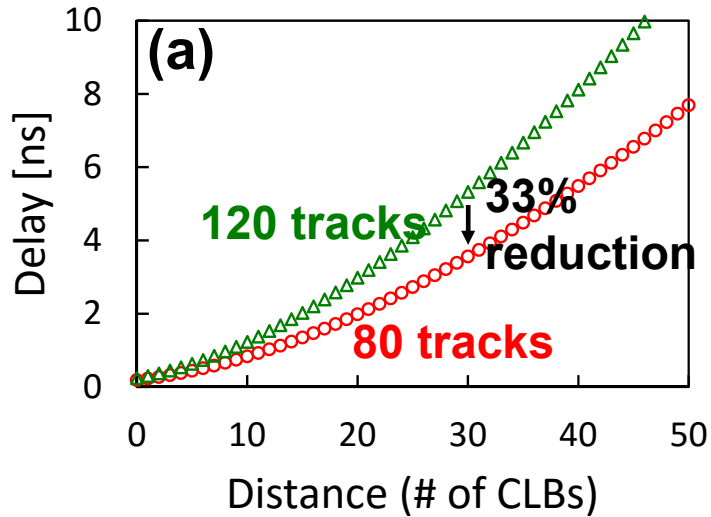
Bi-directional
 → Higher usage
 → **Smaller crossbar**



**On-demand
 repeater
 insertion**

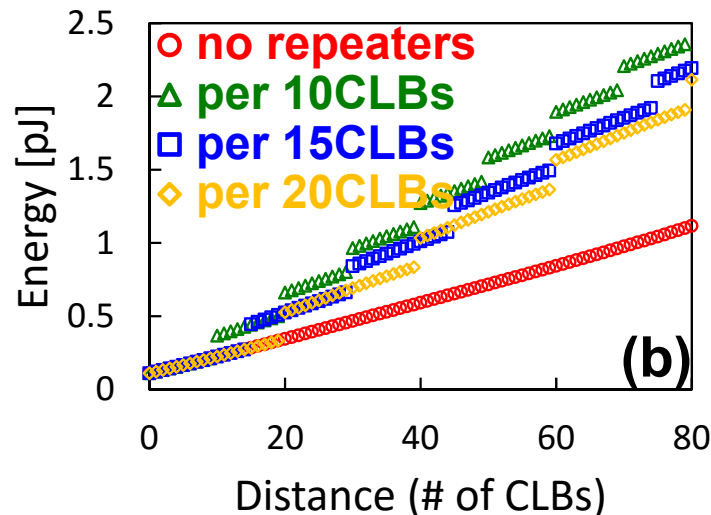
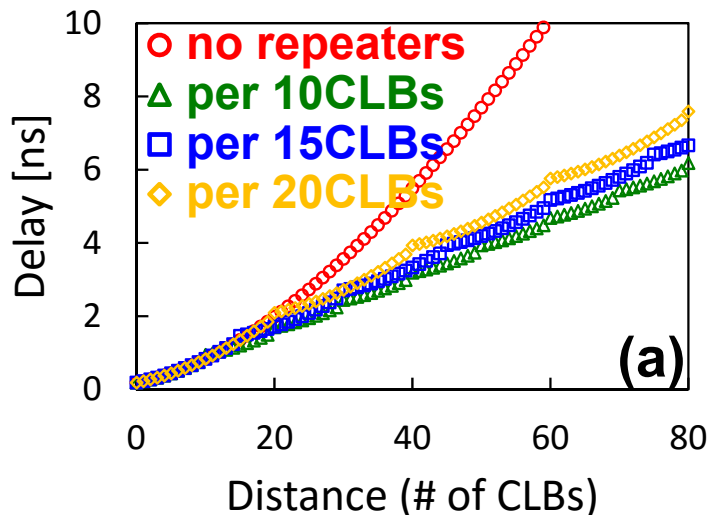


Interconnect Performance Evaluation (65nm)



Smaller crossbar thanks to bidirectional signaling reduces delay and energy.

117x80 or 157x120 crossbars
No repeaters
@1.0V



Delay/energy can be optimized by flexible buffering.

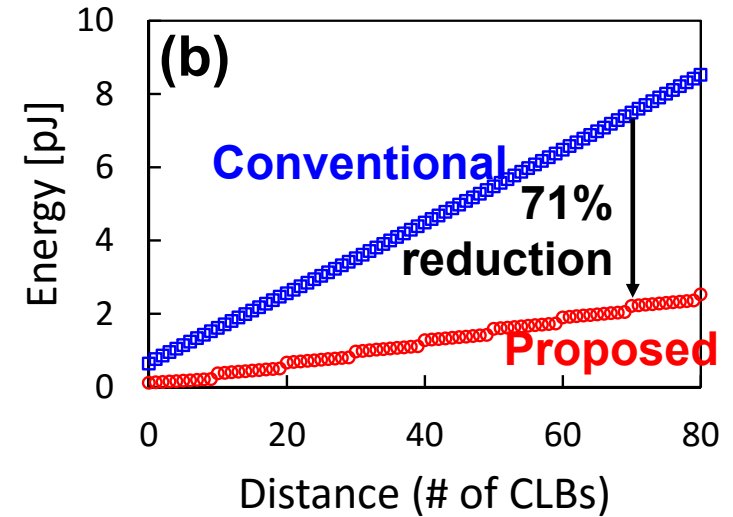
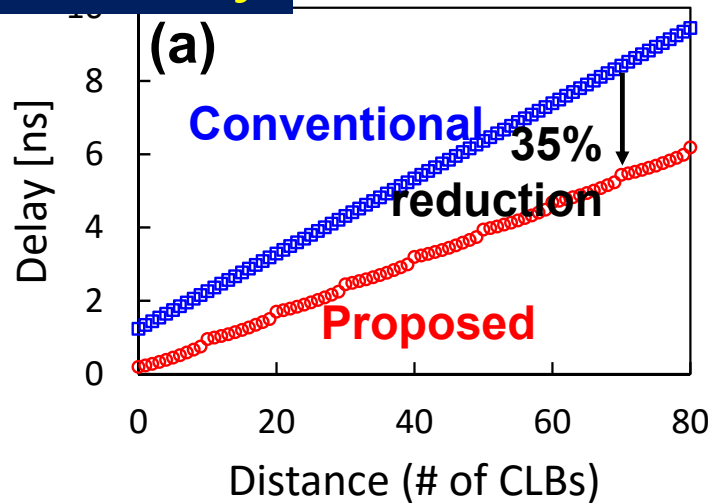
117x80 crossbar
@1.0V

Comparison w/ SRAM-based FPGA (TMG+SRAM crossbar)

26X higher area density

1.0V

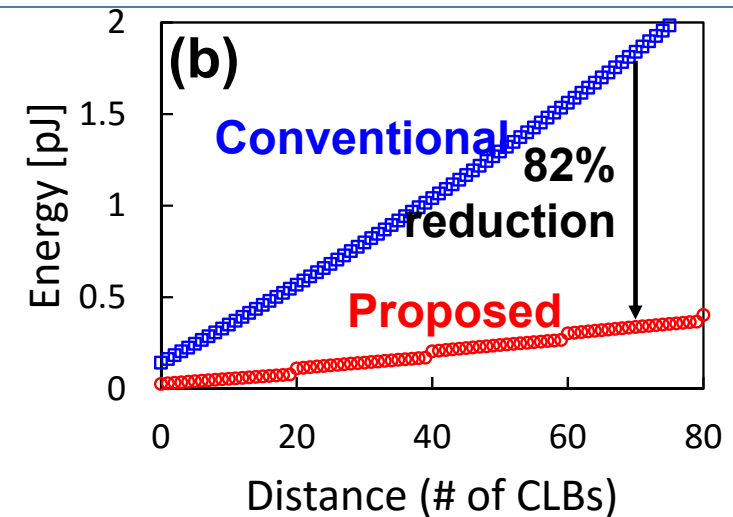
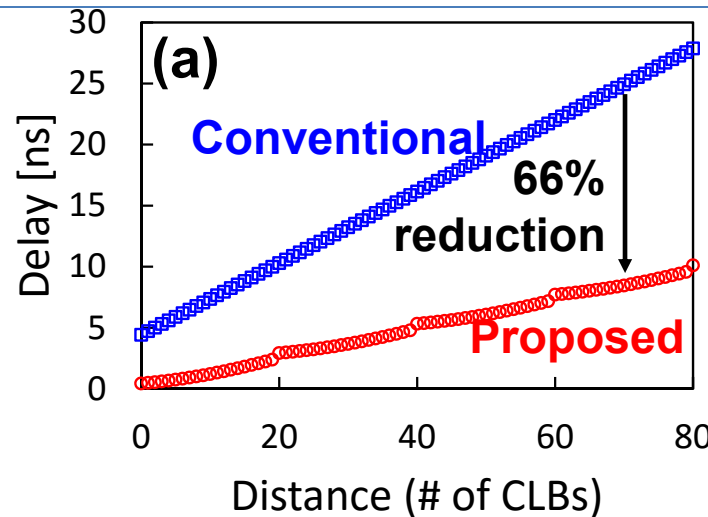
117x80 crossbar
repeater inserted



0.5V

**On-R of via-switch
is independent of
supply voltage.**

117x80 crossbar
repeater inserted



Conclusion

- Proposed a highly-dense reconfigurable architecture that exploits via-switch.
 - 26X higher density
 - Interconnection delay is reduced by 35% (1.0V) and 66% (0.5V)
 - Interconnection energy is reduced by 71% (1.0V) and 82% (0.5V)
- Future works
 - Import long wire interconnection
 - Application mapping and performance evaluation